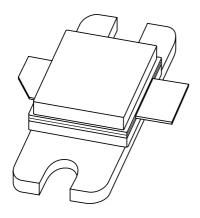
DISCRETE SEMICONDUCTORS

DATA SHEET



BLS3135-50Microwave power transistor

Product specification Supersedes data of 1999 Aug 16 2003 Apr 15





BLS3135-50

FEATURES

- · Suitable for short and medium pulse applications
- Internal input and output matching networks for an easy circuit design
- Emitter ballasting resistors improve ruggedness
- · Gold metallization ensures excellent reliability
- Interdigitated emitter-base structure provides high emitter efficiency
- Multicell geometry improves power sharing and reduces thermal resistance.

APPLICATIONS

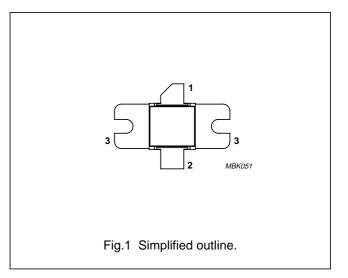
 Common base class-C pulsed power amplifiers for radar applications in the 3.1 to 3.5 GHz band.

DESCRIPTION

NPN silicon planar epitaxial microwave power transistor in a 2-lead rectangular flange package with a ceramic cap (SOT422A) with the common base connected to the flange.

PINNING - SOT422A

PIN	DESCRIPTION				
1	collector				
2	emitter				
3	base; connected to flange				



QUICK REFERENCE DATA

RF performance at $T_h = 25$ °C in a common base class-C test circuit.

MODE OF OPERATION	f	V _{CB}	P _L	G _p	ης
	(GHz)	(V)	(W)	(dB)	(%)
Pulsed, class-C	3.1 to 3.5	40	50	typ. 8	typ. 40

WARNING

Product and environmental safety - toxic materials

This product contains beryllium oxide. The product is entirely safe provided that the BeO disc is not damaged. All persons who handle, use or dispose of this product should be aware of its nature and of the necessary safety precautions. After use, dispose of as chemical or special waste according to the regulations applying at the location of the user. It must never be thrown out with the general or domestic waste.

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	75	V
V _{CES}	collector-emitter voltage	R _{BE} = 0	_	75	V
V _{EBO}	emitter-base voltage	open collector	_	2	V
I _{CM}	peak collector current	$t_p \le 100 \ \mu s; \ \delta \le 10\%$	_	6	Α
P _{tot}	total power dissipation	$t_p = 100 \ \mu s; \ \delta = 10\%; \ T_{mb} = 25 \ ^{\circ}C$	_	80	W
T _{stg}	storage temperature		-65	+200	°C
Tj	operating junction temperature		_	200	°C
T _{sld}	soldering temperature	up to 0.2 mm from ceramic cap; t ≤ 10 s	_	235	°C

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
7	thormal impedance from junction to heatsink	$t_p = 100 \ \mu s; \ \delta = 10\%; \ note \ 1$	0.71	K/W
∠ th j-h	thermal impedance from junction to heatsink	$t_p = 300 \ \mu s; \ \delta = 10\%; \ note \ 1$	0.99	K/W

Note

CHARACTERISTICS

 T_j = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	PARAMETER CONDITIONS			
V _{(BR)CBO}	collector-base breakdown voltage	I _C = 15 mA; open emitter	75	_	V
V _{(BR)CES}	collector-emitter breakdown voltage	$I_C = 15 \text{ mA}; V_{BE} = 0$	75	_	٧
I _{CBO}	collector leakage current	V _{CB} = 40 V; I _E = 0	_	1.5	mA
I _{CES}	collector leakage current	$V_{CE} = 40 \text{ V}; V_{BE} = 0$	_	3	mA
I _{EBO}	emitter leakage current	$V_{EB} = 1.5 \text{ V}; I_{C} = 0$	_	0.3	mA
h _{FE}	DC current gain	V _{CB} = 5 V; I _C = 1.5 A	40	_	

APPLICATION INFORMATION

RF performance at T_h = 25 °C in a common-base test circuit.

MODE OF OPERATION	f (GHz)	V _{CE} (V)	P _L (W)	G _p (dB)	η c (%)
Class-C; $t_p = 100 \ \mu s$; $\delta = 10\%$	3.1 to 3.5	40	≥50	≥7	≥35
			typ. 55	typ. 8	typ. 40

^{1.} Equivalent thermal impedance under pulsed microwave operating conditions. Measured with IR-scan with 20 μ m spot size at hotspot.

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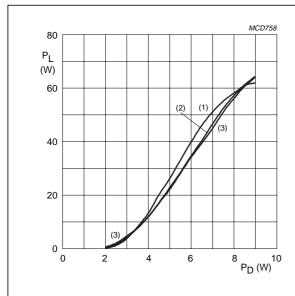
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Typical impedance

FREQUENCY (GHZ)	Z _S (Ω)	Z _L (Ω)
3.1	23.5 – j 5.6	7.8 – j 3.7
3.2	23.6 – j 4.3	7.3 – j 4.1
3.3	23.8 – j 2.9	6.6 – j 4.3
3.4	24.3 – j 1.6	5.8 – j 4.2
3.5	24.9 – j 0.3	5.1 – j 4.1

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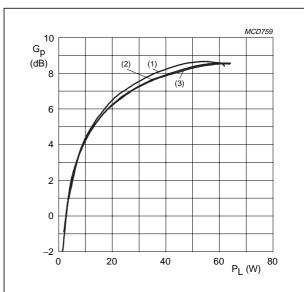
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 V_{CB} = 40 V; class-C; t_p = 100 μ s; δ = 10%.

- (1) f = 3.5 GHz.
- (2) f = 3.3 GHz.
- (3) f = 3.1 GHz.

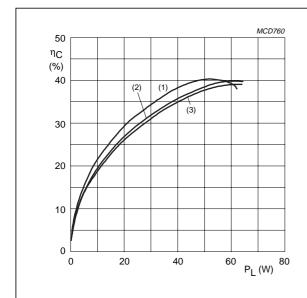
Fig.2 load power as a function of drive power; typical values.



 V_{CB} = 40 V; class-C; P_{L} = 50 W; t_{p} = 100 μ s; δ = 10%.

- (1) f = 3.5 GHz.
- (2) f = 3.3 GHz.
- (3) f = 3.1 GHz.

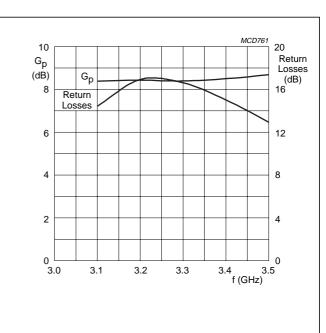
Fig.3 Power gain as a function of load power; typical values.



 V_{CB} = 40 V; class-C; t_p = 100 $\mu s; \, \delta$ = 10%.

- (1) f = 3.5 GHz.
- (2) f = 3.3 GHz.
- (3) f = 3.1 GHz.

Fig.4 Collector efficiency as a function of load power; typical values.

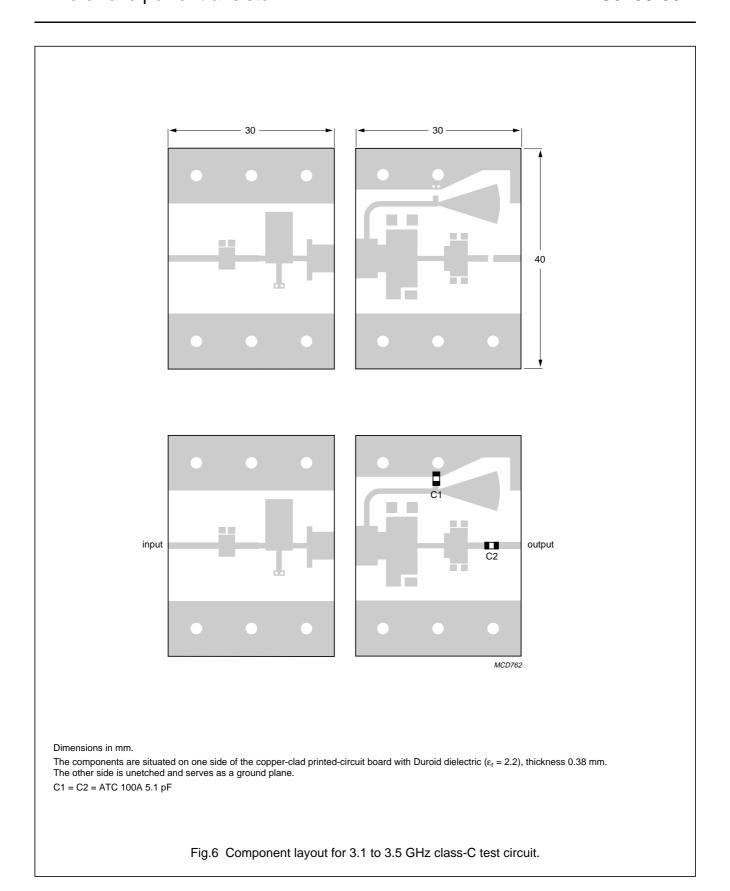


 V_{CB} = 40 V; class-C; P_L = 50 W; t_p = 100 $\mu s;$ δ = 10%.

Fig.5 Power gain and input return losses as functions of frequency; typical values.

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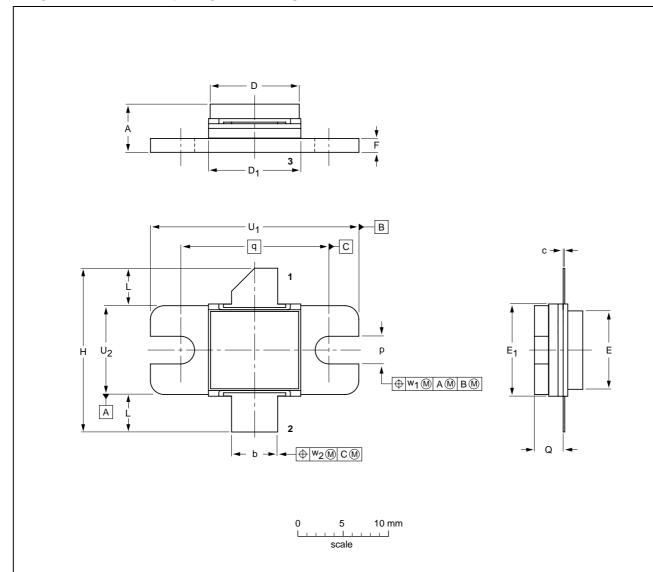
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PACKAGE OUTLINE

Flanged hermetic ceramic package; 2 mounting holes; 2 leads

SOT422A



DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

UNIT	Α	b	С	D	D ₁	E	E ₁	F	н	L	р	ď	q	U ₁	U ₂	w ₁	w ₂
mm	5.72 4.83	5.21 4.95	0.13 0.08	9.93 9.68	10.29 10.03	8.76 8.51	10.29 10.03	1.58 1.47	19.18 17.65	4.52 3.74	3.43 3.18	3.35 2.92	16.51	22.99 22.73	9.91 9.65	0.25	0.76
inches	0.225 0.190	0.205 0.195	0.005 0.003	0.391 0.381	0.405 0.395	0.345 0.335	0.405 0.395	0.062 0.058	0.755 0.695	0.178 0.147	0.135 0.125	0.132 0.115	0.65	0.905 0.895	0.390 0.380	0.01	0.03

OUTLINE	LINE REFERENCES					ISSUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT422A						99-03-29

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DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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